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FQA9P25

250V P-Channel MOSFET

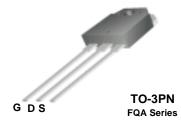
General Description

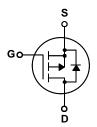
These P-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology is especially tailored to minimize on-state resistance, provide superior switching performance, and withstand a high energy pulse in the avalanche and commutation modes. These devices are well suited for high efficiency switching DC/DC converters.

Features

- -10.5A, -250V, $R_{DS(on)} = 0.62\Omega$ @V_{GS} = -10 V Low gate charge (typical 29 nC)
- Low Crss (typical 27 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		FQA9P25	Units	
V _{DSS}	Drain-Source Voltage		-250	V	
I _D	Drain Current - Continuous (T _C = 25°	°C)	-10.5	А	
	- Continuous (T _C = 100°C)		-6.6	А	
I _{DM}	Drain Current - Pulsed	(Note 1)	-42	А	
V_{GSS}	Gate-Source Voltage		± 30	V	
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	650	mJ	
I _{AR}	Avalanche Current	(Note 1)	-10.5	А	
E _{AR}	Repetitive Avalanche Energy	(Note 1)	15	mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	-5.5	V/ns	
P _D	Power Dissipation (T _C = 25°C)		150	W	
	- Derate above 25°C		1.2	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C	
TL	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C	

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		0.83	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.24		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		40	°C/W

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V, } I_D = -250 \mu\text{A}$	-250			V
ΔBV_{DSS} / ΔT_{J}	Breakdown Voltage Temperature Coefficient	I_D = -250 μA, Referenced to 25°0		-0.2		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -250 V, V _{GS} = 0 V			-1	μΑ
		V _{DS} = -200 V, T _C = 125°C			-10	μА
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = -30 V, V _{DS} = 0 V			-100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
On Cha	aracteristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	-3.0		-5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = -10 V, I _D = -5.25 A		0.48	0.62	Ω
9 _{FS}	Forward Transconductance	V _{DS} = -40 V, I _D = -5.25 A (Note 4		6.1		S
C _{iss}	Input Capacitance Output Capacitance	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz		910 170	1180 220	pF pF
	' '	50				•
C _{rss}	Reverse Transfer Capacitance	1		27	35	pF
Switchi	ing Characteristics					
t _{d(on)}	Turn-On Delay Time	V 425 V I 0.4 A		20	50	ns
t _r	Turn-On Rise Time	$V_{DD} = -125 \text{ V}, I_{D} = -9.4 \text{ A},$ $R_{G} = 25 \Omega$		150	310	ns
t _{d(off)}	Turn-Off Delay Time	NG = 23 22		45	100	ns
t _f	Turn-Off Fall Time	(Note 4, 5	5)	65	140	ns
Qg	Total Gate Charge	V _{DS} = -200 V, I _D = -9.4 A,		29	38	nC
Q _{gs}	Gate-Source Charge	$V_{GS} = -10 \text{ V}$		7.6		nC
Q _{gd}	Gate-Drain Charge	(Note 4, 5	5)	14		nC
Drain-S	Source Diode Characteristics a	nd Maximum Ratings	·			
I _S	Maximum Continuous Drain-Source Diode Forward Current				-10.5	Α
I _{SM}	Maximum Pulsed Drain-Source Diode F	Forward Current			-42	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = -10.5 \text{ A}$			-5.0	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{S} = -9.4 \text{ A},$		190		ns
Q _{rr}	Reverse Recovery Charge	$dI_F / dt = 100 A/\mu s$ (Note 4)		1.45		μС

- **Notes:**1. Repetitive Rating: Pulse width limited by maximum junction temperature 2. L = 9.4mH, I_{AS} = -10.5A, V_{DD} = -50V, R_G = 25 Ω, Starting T_J = 25°C 3. I_{SD} ≤ -9.4A, di/dt ≤ 300A/μs, V_{DD} ≤ BV_{DSS}, Starting T_J = 25°C 4. Pulse Test: Pulse width ≤ 300µs, Duty cycle ≤ 2% 5. Essentially independent of operating temperature

Typical Characteristics

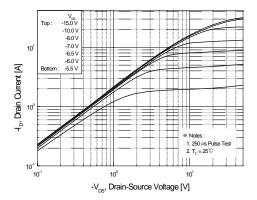


Figure 1. On-Region Characteristics

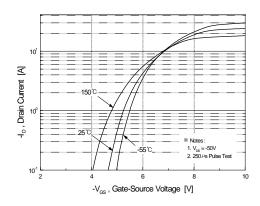


Figure 2. Transfer Characteristics

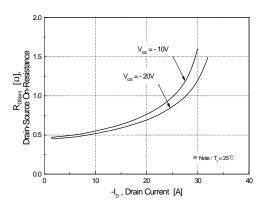


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

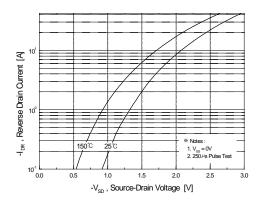


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

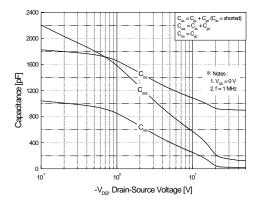


Figure 5. Capacitance Characteristics

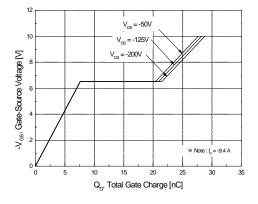
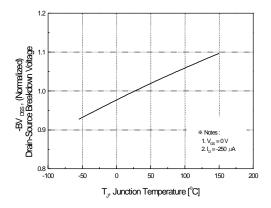


Figure 6. Gate Charge Characteristics

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Typical Characteristics (Continued)



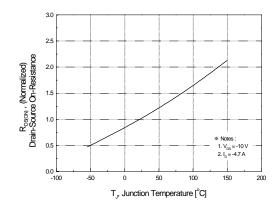
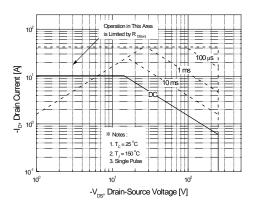


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



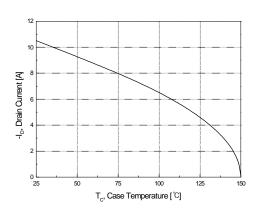


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

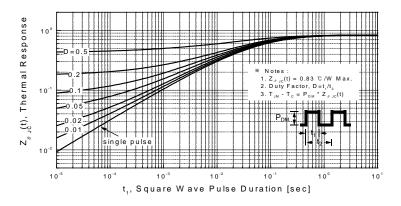
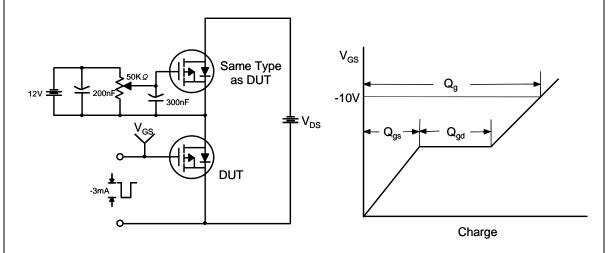


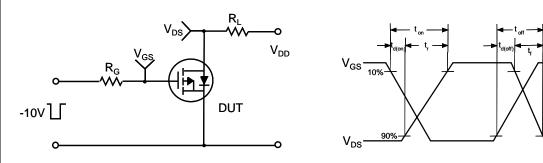
Figure 11. Transient Thermal Response Curve

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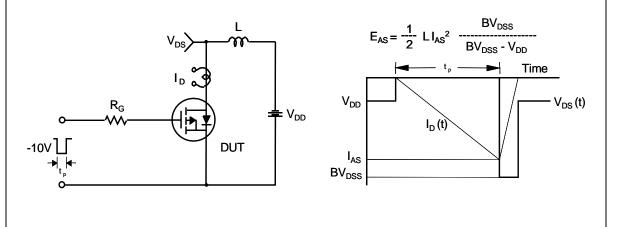
Gate Charge Test Circuit & Waveform



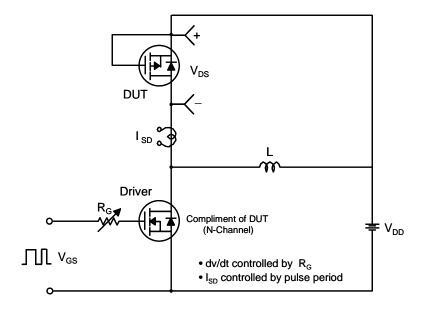
Resistive Switching Test Circuit & Waveforms

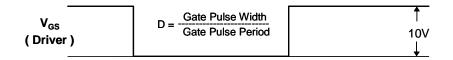


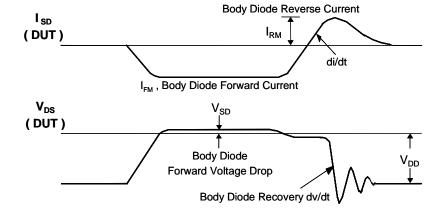
Unclamped Inductive Switching Test Circuit & Waveforms



Peak Diode Recovery dv/dt Test Circuit & Waveforms







Mechanical Dimensions TO-3PN ø3.30 3.10 15,80 15,40 (R0.50) -5.20 4.80 18.90 18,50 (1.85) -2,20 1.80 2.60 2.20 3,20 2.80 20.30 19.70 **⊕** Ø0.55**⋈** 1.20 5.45 5.45 (R0,50)

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